

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

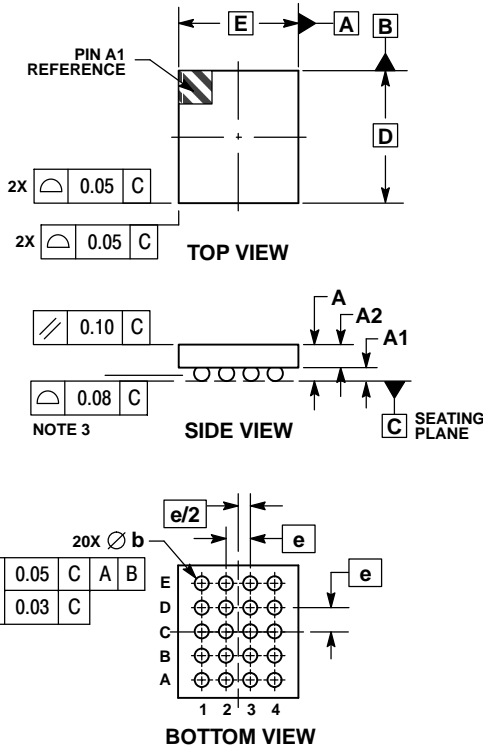
ON Semiconductor®



SCALE 4:1

WLCSP20 2.187x1.987  
CASE 567JV  
ISSUE B

DATE 27 JAN 2015

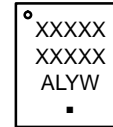


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.65
A1	0.17	0.23
A2	0.38 REF	
b	0.23	0.29
D	2.187 BSC	
E	1.987 BSC	
e	0.40 BSC	

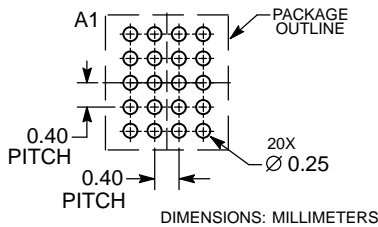
**GENERIC MARKING DIAGRAM\***



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	WLCSP20 2.187X1.987	<b>PAGE 1 OF 2</b>



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY P. JOHNSON.	23 APR 2014
A	CHANGED DIE SIZE FROM 2.01X1.80 TO 2.189X1.982. REQ. BY P. JOHNSON.	06 MAY 2014
B	CHANGED DIE SIZE FROM 2.189X1.982 TO 2.187X1.987. REQ. BY B. BLAUER. MODIFIED DIMENSIONS A1 AND b.	27 JAN 2015

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